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INFORMATION DISCLOSURE STATEMENT
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Application Number 10/084,563
Filing Date 2/26/2002
First Named Inventor Sergey Lopatin
Attorney Docket No. P1410

Sheet 1 of 1

U.S. PATENT DOCUMENTS

Examiner Initial	Cite No.	U.S. Patent Document Number	Name of Patentee or Applicant of Cited Documents	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
Lee	1	6,197,181 B1	Chen, Lin Lin	3/6/2001	
Lo	2	6,022,808	Nogami, et al.	2/8/2000	

FOREIGN PATENT DOCUMENTS

Examiner Initials	Cite No.	Foreign Patent Document Office Number Code	Name of Patentee or Applicant of Cited document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

Examiner Initials	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.
Lee	1	PETER VAN ZANT, "Microchip Fabrication: A Practical Guide to Semiconductor Processing", 3 rd Ed., p. 392 and 397 (1997)
Lee	2	A. Krishnamoorthy, D. Duquette and S. Murarka, "Electrochemical Codeposition and Electrical Characterization of a Copper-Zinc Alloy Metallization", in edited by Andricacos, et al., Electrochem Society Symposium Proceedings, Vol. 99-9, May 3-6, Seattle, p. 212
Lee	3	J. Cunningham, "Using Electrochemistry to Improve Copper Interconnect", in Semiconductor International, Spring 2000 (May)
Lee	4	L. Chen and T. Ritzdorf, "ECD Seed Layer for Inlaid Copper Metallization" in edited by Andricacos, et al., Electrochem Society Proceedings, Vol. 99-9, May 3-6, Seattle, p. 122

Examiner Signature: *Hein Ming Lee* Date Considered: *4/2/03*

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹Unique citation designation number. ²See attached Kinds of U.S. Patent Documents. ³Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶Applicant is to place a check mark here if English Language Translation is attached.